

ABSTRACT OF THE DISCLOSURE

Formed first is a template having openings located to correspond to a pattern in which a plurality of semiconductor laser elements are to be arranged. Then, the template is held on the principal surface of a mounting wafer onto which the semiconductor elements 5 are to be arranged. Subsequently, the semiconductor laser elements are dispersed into a fluid, and the semiconductor-laser-element-dispersed fluid is poured over the wafer on which the template is held. In this manner, the semiconductor laser elements are disposed into the respective openings of the template in a self-aligned manner.